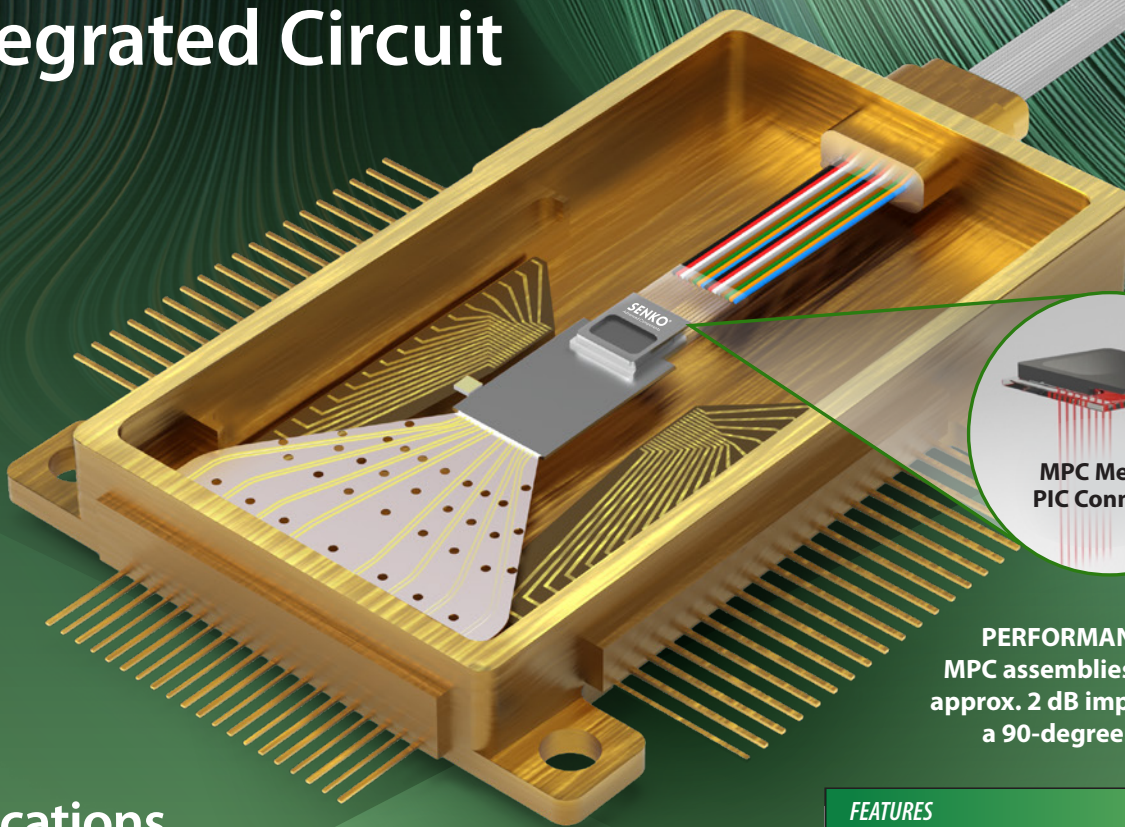


Unlocking the future  
of quantum information  
processing

# QPIC PACKAGING MODULE

Photonic  
Integrated Circuit



MPC Metallic  
PIC Connector

**PERFORMANCE BOOST**  
MPC assemblies demonstrate  
approx. 2 dB improvement over  
a 90-degree fiber array

## Applications

- Quantum Computing
- Quantum Communication
- Quantum Sensing and Metrology
- Quantum Cryptography
- Quantum Net
- Quantum Key Distribution

## FEATURES

- Ultra low loss
- Templates available to simplify deployment
- Compatible with most QPIC designs



**QPIC PACKAGING MODULE**

Innovation Through Collaboration



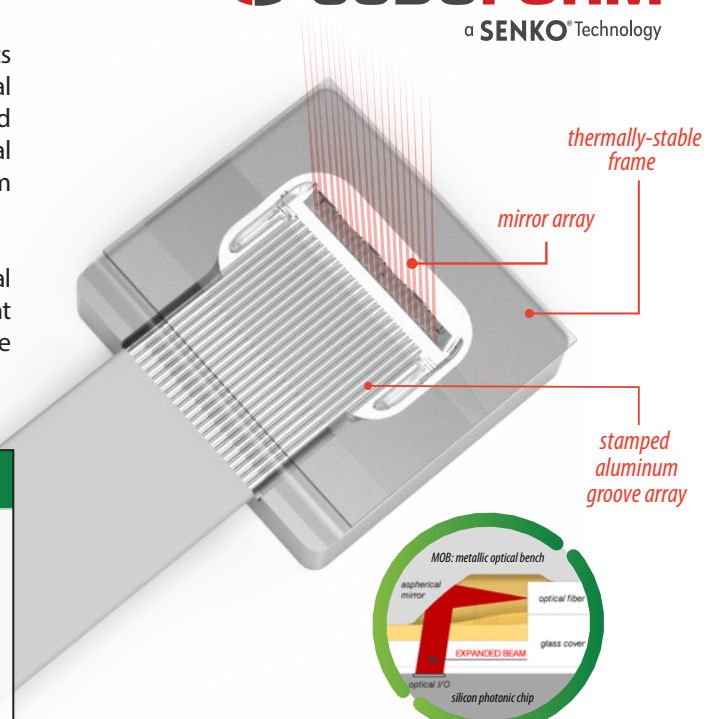
## MPC Metallic PIC Connector

Quantum photonic integrated circuits (QPICs) harness quantum mechanics and optics to solve complex problems exponentially faster than classical computers. Unlike traditional electronic interconnects, which are hindered by the delicate nature of quantum states and single photon sources, optical interconnects offer a scalable and efficient solution for connecting quantum components.

Metallic PIC connectors are constructed from stamped metallic optical benches. They include micro mirror arrays for folding-and-focusing light beams between optical fibers and photonic devices. Mirror designs are available for single-mode and PM applications.

## CUDOFORM

a SENKO® Technology



**MPC IS CUSTOMIZABLE TO SUIT A WIDE VARIETY OF APPLICATIONS**

<p><b>MPC 8 fibers*</b> 250 μm</p> <p>3.2 mm</p>	<p><b>MPC 16 fibers</b> 127 μm</p> <p>4.4 mm</p>	<p><b>MPC 20 fibers</b> 127 μm</p> <p>5.0 mm</p>
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*NOTE: Products shown are permanent attached  
\*8 fibers suitable for QPIC Packaging Module*

Contact [QPICPAC@Senko.com](mailto:QPICPAC@Senko.com)  
for availability and to learn more

